



General Description

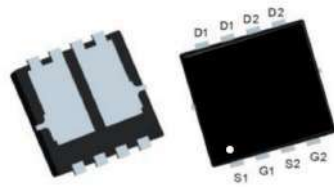
- Trench Power LV MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low $R_{DS(ON)}$

Applications

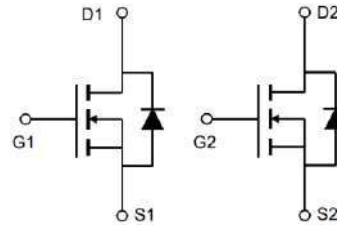
- High current load applications
- Load switching
- Hard switched and high frequency circuits
- Uninterruptible power supply

Product Summary

V_{DS}	40	V
$R_{DS(on),Typ} @ V_{GS}=10V$	15	m Ω
I_D	20	A



PDFN 3.3x3.3-8



NMOS

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-source Voltage		V_{DS}	40	V
Gate-source Voltage		V_{GS}	± 20	V
Drain Current	$T_C=25^\circ\text{C}$	I_D	20	A
	$T_C=100^\circ\text{C}$		16	
Pulsed Drain Current ^A		I_{DM}	80	A
Single Pulse Avalanche Energy ^B		E_{AS}	70	mJ
Total Power Dissipation	$T_C=25^\circ\text{C}$	P_D	21	W
Thermal Resistance Junction-to-Ambient		$R_{\theta JA}$	35	$^\circ\text{C}/\text{W}$
Thermal Resistance Junction-to-Case		$R_{\theta JC}$	3.0	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature Range		T_J, T_{STG}	-55~+150	$^\circ\text{C}$

Electrical Characteristics (T_J=25°C unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0V, I _D =250μA	40			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =40V, V _{GS} =0V			1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} = ±20V, V _{DS} =0V			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D =250μA	1.0	1.5	2.5	V
Static Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} = 10V, I _D =20A		15	19	mΩ
		V _{GS} = 4.5V, I _D =10A		18	25	
Diode Forward Voltage	V _{SD}	I _S =20A, V _{GS} =0V		0.7	1.2	V
Dynamic Parameters						
Input Capacitance	C _{iss}	V _{DS} =20V, V _{GS} =0V, f=1MHZ		800		pF
Output Capacitance	C _{oss}			112		
Reverse Transfer Capacitance	C _{rss}			94		
Switching Parameters						
Total Gate Charge	Q _g	V _{GS} =10V, V _{DS} =20V, I _D =20A		23.6		nC
Gate-Source Charge	Q _{gs}			4.4		
Gate-Drain Charge	Q _{gd}			6.3		
Reverse Recovery Charge	Q _{rr}	I _F =20A, di/dt=100A/us		0.4		ns
Reverse Recovery Time	t _{rr}			7		
Turn-on Delay Time	t _{D(on)}	V _{GS} =10V, V _{DD} =20V, I _D =2A, R _{GEN} =3Ω		10		ns
Turn-on Rise Time	t _r			56		
Turn-off Delay Time	t _{D(off)}			27		
Turn-off fall Time	t _f			72		

A. Pulse Test: Pulse Width ≤ 300us, Duty cycle ≤ 2%.

B. R_{θJA} is the sum of the junction-to-case and case-to-ambient thermal resistance, where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{θJC} is guaranteed by design, while R_{θJA} is determined by the board design. The maximum rating presented here is based on mounting on a 1 in 2 pad of 2oz copper.



Typical Performance Characteristics

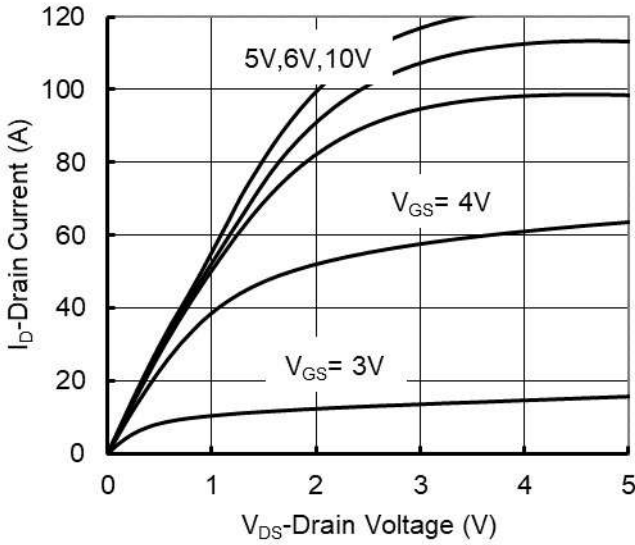


Figure 1. Output Characteristics

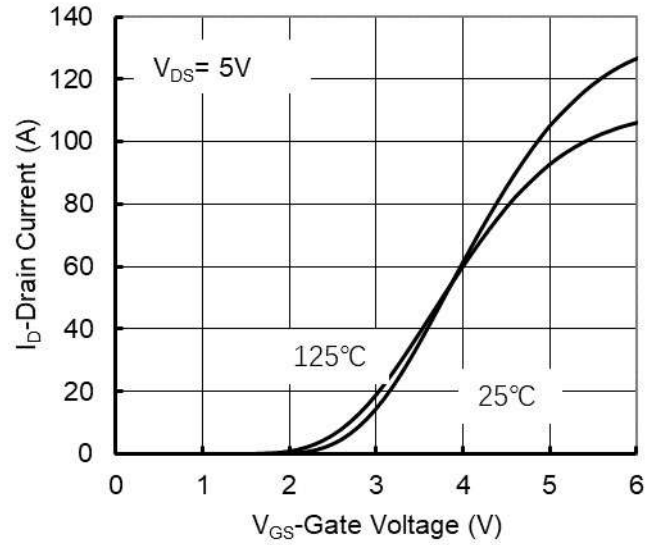


Figure 2. Transfer Characteristics

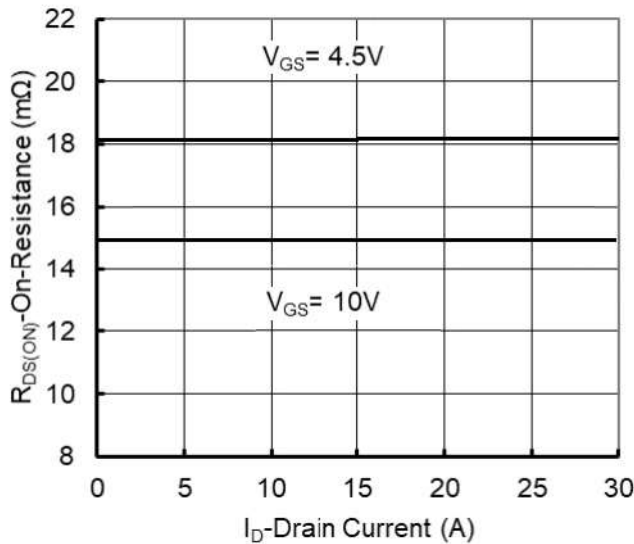


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

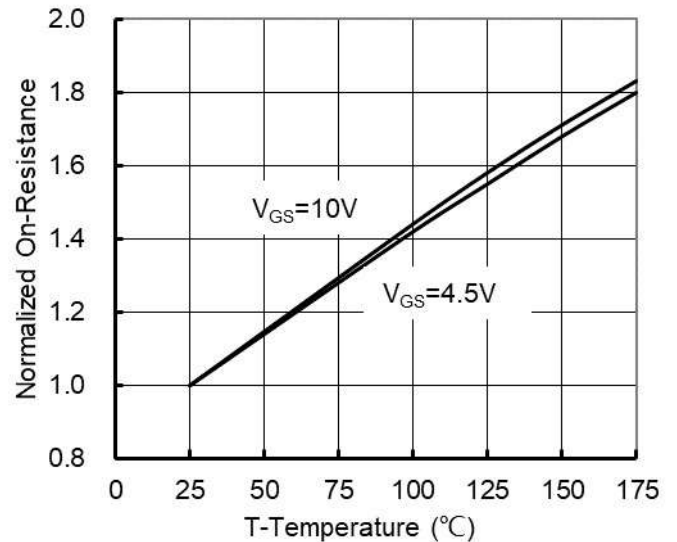


Figure 4. On-Resistance vs. Junction Temperature

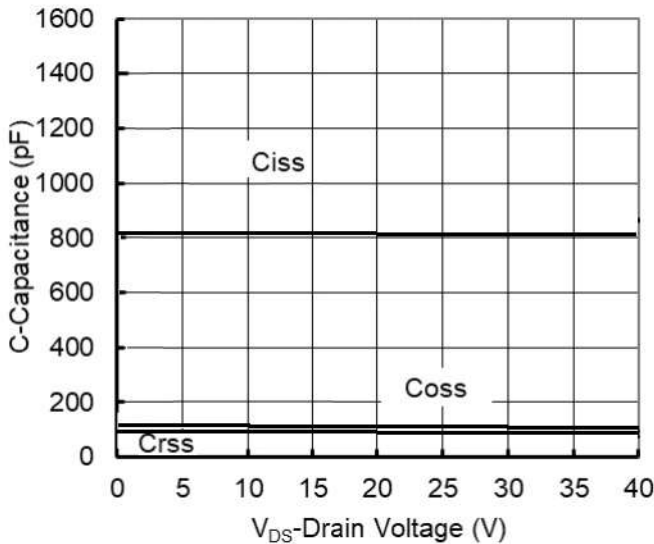


Figure 5. Capacitance Characteristics

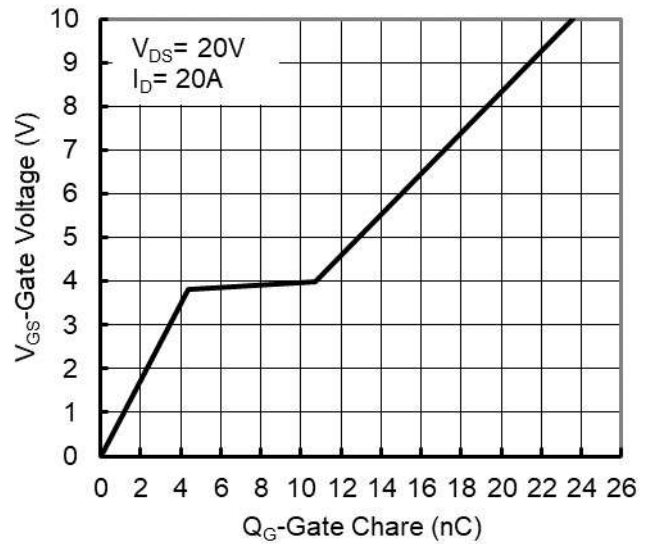


Figure 6. Gate Charge

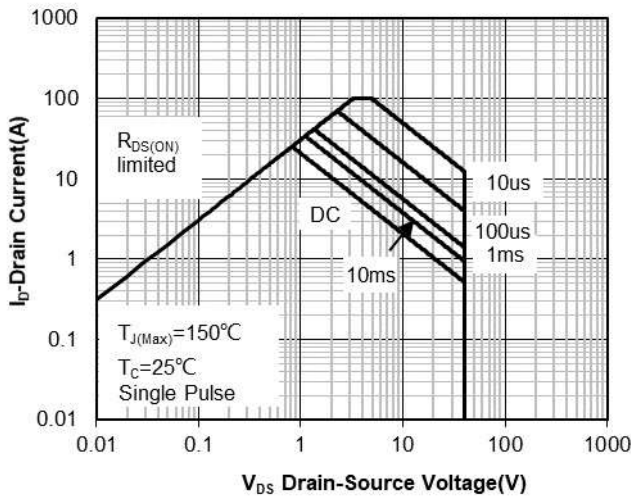


Figure 7. Safe Operation Area

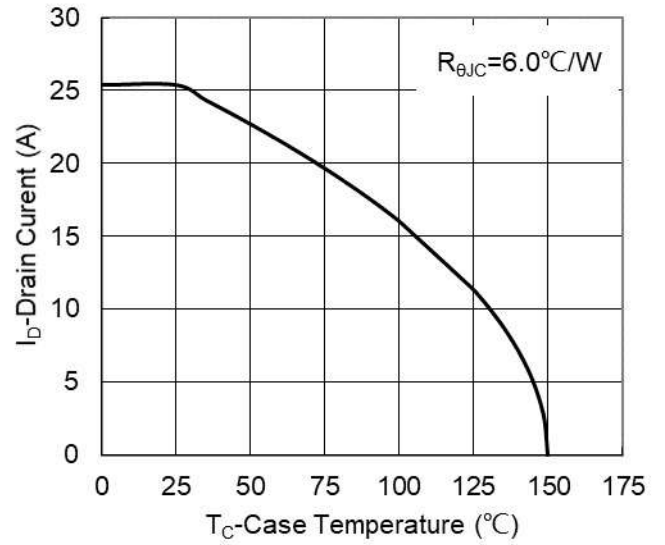


Figure 8. Maximum Continuous Drain Current vs Case Temperature

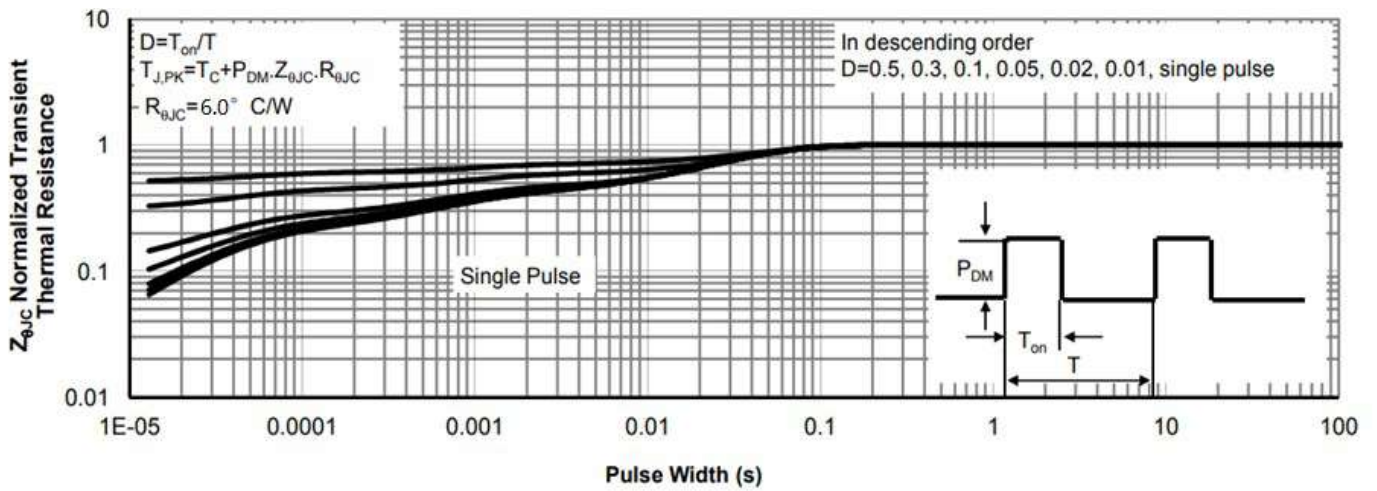
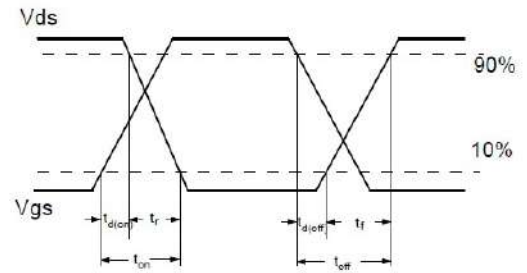
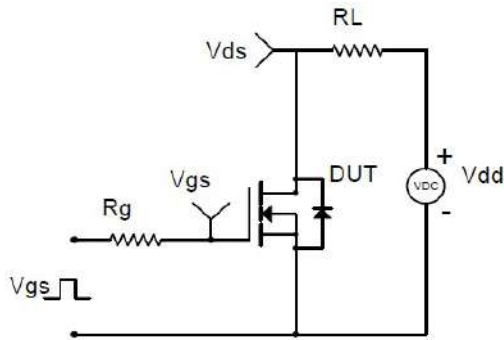
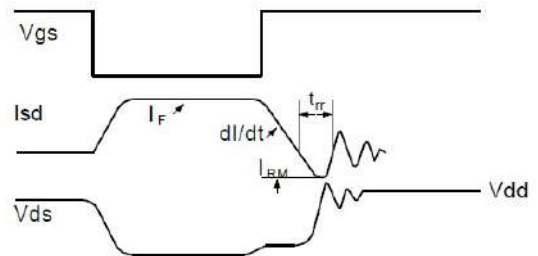
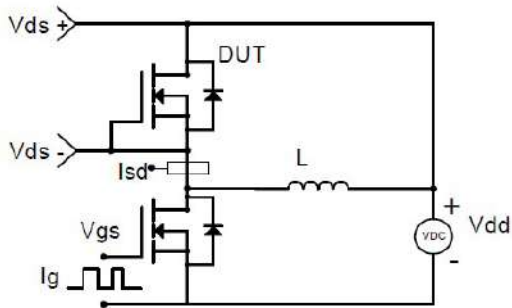


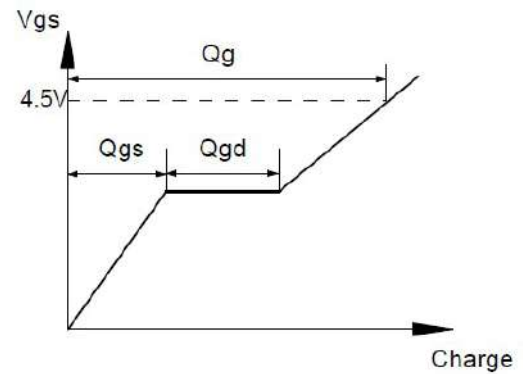
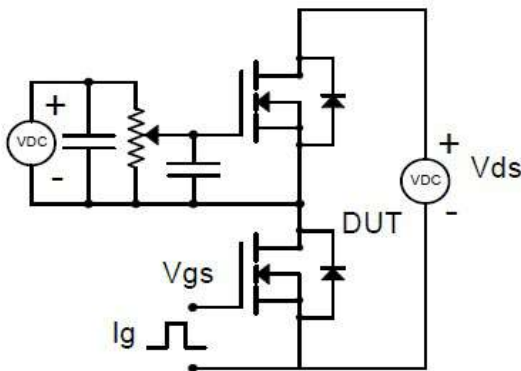
Figure 9. Normalized Maximum Transient Thermal Impedance



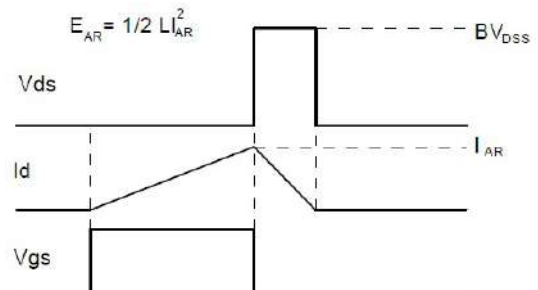
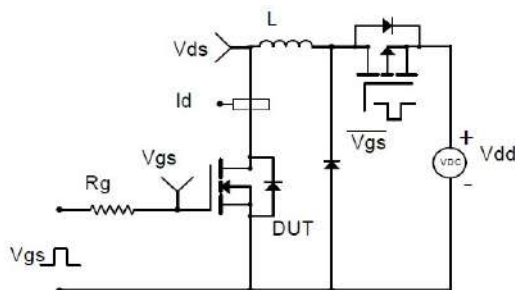
Resistive Switching Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



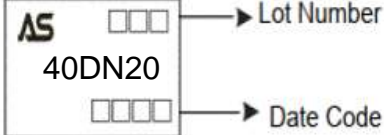
Gate Charge Test Circuit & Waveform



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

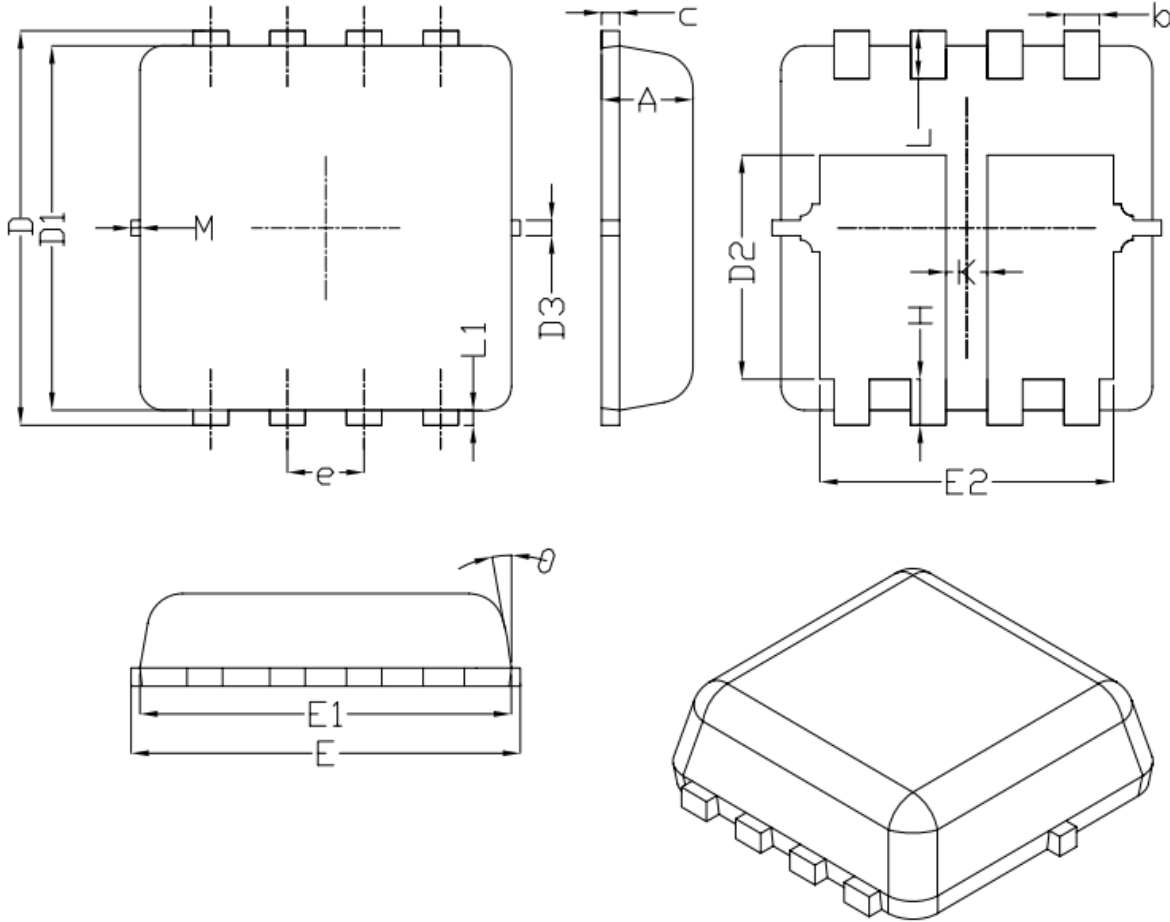
Ordering and Marking Information

Ordering Device No.	Marking	Package	Packing	Quantity
ASDM40DN20E-R	40DN20	PDFN3.3*3.3-8	Tape&Reel	5000/Reel

PACKAGE	MARKING
PDFN3.3*3.3-8	 <p>AS □□□ → Lot Number 40DN20 □□□□ → Date Code</p>



Dual PDFN3.3*3.3-8 Package Outline Data



Symbol	Dimensions (unit: mm)		
	Min	Typ	Max
A	0.70	0.75	0.80
b	0.25	0.30	0.35
c	0.10	0.15	0.25
D	3.25	3.35	3.45
D1	3.00	3.10	3.20
D2	1.78	1.88	1.98
D3	--	0.13	--
E	3.20	3.30	3.40
E1	3.00	3.15	3.20
E2	2.39	2.49	2.59
e	0.65 BSC		
H	0.30	0.39	0.50
L	0.30	0.40	0.50
L1	--	0.13	--
K	0.30	--	--
θ	--	10°	12°
M	*	*	0.15
* Not Specified			

Notes:

1. Refer to JEDEC MO-240 variation CA.
2. Dimensions "D1" and "E1" do NOT include mold flash protrusions or gate burrs.
3. Dimensions "D1" and "E1" include interterminal flash or protrusion. Interterminal flash or protrusion shall not exceed 0.25mm per side.

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